

	Hit s	Search Text	DBs
33	7	((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) and ((cover or lid or (protective near9 (layer or coat\$4)) or encapsula\$4) same ((transparent or transmissive or transmitting) near9 (portion or region or area)) same (support or (spac\$4 near9 structure) or spacer) same (height or thickness) same (gap or spac\$3 or distance or depth) same ((imag\$3 near4 circuit\$4) or circuit\$3 or die or (wafer near9 die)))	US-PGPUB
34	16	((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) and ((cover or lid or (protective near9 (layer or coat\$4)) or encapsula\$4) same ((transparent or transmissive or transmitting) near9 (portion or region or area)) same (support or (spac\$4 near9 structure) or spacer) same (height or thickness) same (gap or spac\$3 or distance or depth) same ((imag\$3 near4 circuit\$4) or circuit\$3 or die or (wafer near9 die)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
35	0	((semiconductor or wafer or substrate or wafer or sensor or device) near14 (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) and ((cover or lid or (protective near9 (layer or coat\$4)) or encapsula\$4) same ((transparent or transmissive or transmitting) near9 (portion or region or area)) same (support or (spac\$4 near9 structure) or spacer) same photosensitive same (height or thickness) same (gap or spac\$3 or distance or depth) same ((imag\$3 near4 circuit\$4) or circuit\$3 or die or (wafer near9 die)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
36	1	((semiconductor or wafer or substrate or wafer or sensor or device) or (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) and ((cover or lid or (protective near9 (layer or coat\$4)) or encapsula\$4) same ((transparent or transmissive or transmitting) near9 (plate or portion or region or area)) same (support or (spac\$4 near9 structure) or spacer) same photosensitive same (height or thickness or gap or spac\$3 or distance or depth) same ((imag\$3 near4 circuit\$4) or circuit\$3 or die or (wafer near9 die)))	US-PGPUB

	Hits	Search Text	DBs
37	1	((semiconductor or wafer or substrate or wafer or sensor or device) or (die or circuit\$5 or (integrated near9 circuit\$4) or (imag\$4 near9 circuit\$5))) and ((cover or lid or (protective near9 (layer or coat\$4)) or encapsula\$4) same ((transparent or transmissive or transmitting) near9 (plate or portion or region or area)) same (support or (spac\$4 near9 structure) or spacer) same photosensitive same (height or thickness or gap or spac\$3 or distance or depth) same ((imag\$3 near4 circuit\$4) or circuit\$3 or die or (wafer near9 die)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB